Overview

HP EliteBook x360 1040 G8 Notebook PC



- 1. Internal Microphones
- 2. IR Camera LEDs
- 3. Webcam and IR Camera
- 4. Webcam LED
- 5. Glass Clickpad

Left

- 6. Nano Security lock slot (Lock sold separately)
- 7. WWAN SIM (Nano)
- 8. Audio Combo Jack
- 9. SuperSpeed USB Type-A 5Gbps signaling rate (Charging port)

Overview



- 1. Power button
- 2. SuperSpeed USB Type-A 5Gbps signaling rate (Charging port)
- 3. HDMI 2.0 port (Cable not included)

Right

- Thunderbolt[™] 4 with USB4[™] Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)¹
- 5. Thunderbolt[™] 4 with USB4[™] Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)¹
- 6. Battery LED
- 1. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

Overview

AT A GLANCE

- An all metal CNC Aluminum chassis that is .6 inches (1.66 cm) thin (at front) and with a starting weight of 2.9 lbs. (1.31 Kg)
- A 360° convertible notebook with 4 usage modes: Laptop mode, Tablet mode, Tent mode, and Media mode
- Choice of 11th Generation Intel® Core™ i5, i7 Processors with integrated Intel® Iris® Xe Graphics supporting dual channel
 LP DDR4X memory up to 32 GB and solid state storage up to 2 TB
- Intel® EVO configurations available
- Touch display choices include 35.56 cm (14.0") diagonal IPS FHD displays and stunning UHD HDR-400 display. Optional
 Anti-glare screen available on FHD panels. Get added protection in open or public places with the optional HP Sure View
 Reflect integrated privacy screen
- Ultimate connectivity with dual Thunderbolt[™] 4² with USB4 support ports, dual USB 3.1 Gen1 charging ports, and HDMI
 2.0. Stay connected where you need to with additional choices of 5G or 4G/LTE WWAN, WLAN and optional Thunderbolt[™]
 Docking (Sold separately)
- Featuring HP Quiet Keyboard with the HP Programmable key. The power button, HP Sure Shutter and the fingerprint sensor are also located on the keyboard
- An optional HP Rechargeable Active Pen 31 with Magnetic Attach and 4096 Levels of pressure
- Never forget your password with your choice of simple authentication methods, including the IR camera for face recognition and Touch Fingerprint Sensor for Windows Hello
- Enterprise grade security with HP Sure Sense, HP Sure Start, HP Sure Shutter, HP Sure View Reflect (optional), HP Sure Run, HP Sure Recover with Embedded Reimaging, HP Sure Click, HP Tamper Lock and Touch Fingerprint sensor
- HP Sure Shutter industry's 1st camera with an electric shutter. The on/off button for this shutter is located on the function row of the keyboard.
- Two choices for the system battery: a 54.5 Wh battery for lighter configurations and a 78.5 Wh battery for the longest battery life. Battery Life up to 14 hours 45 minutes (54 Wh battery) (MobileMark2018) and up to 22 hours (78 Wh battery) (MobileMark2018).
- Al based HP Context Aware to maximize performance when working at a table, comfort when working from your lap, and responsiveness when working on the go.
- HP Presence Aware automatically locks your system when you leave and seamlessly seamlessly authenticates with Window's Hello
- HP Dynamic Audio, a new AI-based audio experience, tunes output to speech, music, and movies all while suppressing background noise. (Planned to be available March 2021)
- HP Sound Calibration to uniquely tune end user headphone audio. (Planned to be available March 2021)
- Passed 19 MIL-STD 810H tests¹
- MIL-STD 810H is not intended to demonstrate fitness of U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.
- 2. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



PRODUCT NAME

HP EliteBook x360 1040 G8 Notebook PC

OPERATING SYSTEM

Preinstalled Windows 10 Pro 64 – HP recommends Windows 10 Pro for business ¹

Windows 10 Pro 64 (National Academic License) 1,2

Windows 10 Home 64 1

Windows 10 Home Single Language 64 1

Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement) 1

FreeDOS

- 1. Not all features are available in all editions or versions of Window. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply, and additional requirements may apply over time for updates. See http://www.windows.com/.
- 2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282.

PROCESSORS

Intel® Core™ i7-1185G7 (3.0 GHz base frequency, up to 4.8 GHz frequency with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores) supports Intel® vPro® Technology ^{3,45,6}, Intel® Core™ i7-1165G7 (Up to 4.7 GHz with Intel® Turbo Boost Technology, 12 MB L3 cache, 4 cores) ^{3,45,6} Intel® Core™ i5-1145G7 (2.6 GHz base frequency, up to 4.4 GHz frequency with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) supports Intel® vPro® Technology ^{3,45,6} Intel® Core™ i5-1135G7 (Up to 4.2 GHz with Intel® Turbo Boost Technology, 8 MB L3 cache, 4 cores) ^{3,45,6}

Processor Family

11th Generation Intel® Core™ i7 processor (i7-1185G7 and 1165G7) ⁶
11th Generation Intel® Core™ i5 processor (i5-1145G7 and 1135G7) ⁶

- 3. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.
- 4. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
- 5. Intel® Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.
- 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.



CHIPSET

Chipset is integrated with processor

GRAPHICS

Integrated

Intel® Iris® Xe Graphics

Supports

Support HD decode DX12 HDMI 2.0 7

7. HDMI cable sold separately.

DISPLAY

Touch

35.6 cm (14") diagonal FHD IPS Ultraslim 2.0mm eDP + PSR2 BrightView touch screen with 0.4mm Gorilla® Glass 5, 400 nits, 72% NTSC (1920 x 1080) 9,10,11

35.6 cm (14") diagonal FHD IPS Ultraslim 2.0mm eDP + PSR2 Anti-Glare touch screen with 0.4mm Gorilla $^{\circ}$ Glass 5, 400 nits, 72% NTSC (1920 x 1080) 9,10,11

35.6 cm (14") diagonal UHD HDR400 IPS Ultraslim 2.0mm eDP + PSR BrightView touch screen with 0.4mm Gorilla® Glass 5, 550 nits, 72% NTSC (3840 x 2160) 9,10,11

HP Sure View Reflect Integrated Privacy Screen 35.6 cm (14") diagonal FHD IPS Ultraslim 2.0mm eDP + PSR BrightView touch screen with 0.4mm Gorilla® Glass 5, 1000 nits, 72% NTSC (1920 x 1080) 9,10,11,12

HP Sure View Reflect Integrated Privacy Screen 35.6 cm (14") diagonal FHD IPS Ultraslim 2.0mm eDP + PSR Anti-Glare touch screen with 0.4mm Gorilla® Glass 5, 1000 nits, 72% NTSC (1920 x 1080) 9,10,11,12

HDMI 2.08

Supports resolutions up to 4K@60Hz

- 8. HDMI cable sold separately.
- 9. FHD/HD content required to view FHD/HD images.
- 10. Resolutions are dependent upon monitor capability, and resolution and color depth settings.
- 11. Actual brightness will be lower with touchscreen or Sure View.
- 12. HP Sure View integrated privacy screen is an optional feature that must be configured at purchase and is designed to function in landscape orientation.



Technical Specifications

STORAGE AND DRIVES

Primary M.2 Storage

128 GB PCIe® Gen3x2 NVMe[™] M.2 SSD TLC¹³
256 GB PCIe® Gen3x4 NVMe[™] M.2 SSD TLC¹³
512 GB PCIe® Gen3x4 NVMe[™] M.2 SSD TLC¹³
1 TB PCIe® Gen3x4 NVMe[™] M.2 SSD TLC¹³
2 TB PCIe® Gen3x4 NVMe[™] M.2 SSD TLC¹³

256 GB PCIe® NVMe™ Value M.2 SSD¹³ 512 GB PCIe® NVMe™ Value M.2 SSD¹³

256 GB PCle® Gen3x4 NVMe™ M.2 SED SS TLC OPAL 2¹³ 512 GB PCle®Gen 3x4 NVMe™ M.2 SED TLC OPAL2¹³

512 Intel® PCIe® NVMe™ QLC M.2 SSD with 32 GB Intel® Optane™ memory H10^{13,14}

13. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

14. Intel® Optane™ H10 memory system acceleration does not replace or increase the DRAM in your system. Requires 8th Gen or higher Intel® Core™ processor, BIOS version with Intel® Optane™ supported, Windows 10 64-bit, and an Intel® Rapid Storage Technology (Intel® RST) driver.

MEMORY

Maximum Memory

32 GB LPDDR4X-4266 SDRAM

Memory

32 GB LPDDR4X-4266 SDRAM ¹⁵ 16 GB LPDDR4X-4266 SDRAM ¹⁵ 8 GB LPDDR4X-4266 SDRAM ¹⁵

Memory Slots

Memory soldered down LPDDR4X, System runs at: 4266 Supports Dual Channel Memory

15. All slots are non-accessible / non-upgradeable.



Technical Specifications

NETWORKING/COMMUNICATIONS

WLAN

Intel® Dual Band Wireless-AX201 802.11a/b/g/n/ac/ax (2x2) Wi-Fi® 6 and Bluetooth® 5 Combo, vPro® 16 Intel® Dual Band Wireless-AX201 802.11a/b/g/n/ac/ax (2x2) Wi-Fi® 6 and Bluetooth® 5 Combo, non-vPro® 16

WWAN

Intel® XMM™ 7360 LTE-Advanced Cat 9 ¹⁸
Qualcomm® Snapdragon™ X55 5G Modem (5G + LTE CAT 20)¹⁹

NFC

NPC300 Near Field Communication Module 20

Miracast

Native Miracast Support 21

16. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

18. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. LTE not available on all products, in all regions.

19. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.

20. Sold separately or as an optional feature.

21. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.

AUDIO/MULTIMEDIA

Audio

Audio by Bang & Olufsen

4 Premium stereo speakers

Microphones (Multi Array including two user facing and two world-facing microphones)

Camera

Hybrid 720p HD camera with integrated electronic privacy shutter, HP Sure Shutter ²²

Note: The on/off button for this shutter is located on the function row of the keyboard.

Sensors

Accelerometer

Magnetometer

Gyroscope



Technical Specifications

Ambient light sensor Hall sensor

22. HD content required to view HD images.

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

HP Quiet Keyboard, spill resistant, Backlit keyboard and Durakeys HP Quiet Keyboard, spill resistant, Backlit keyboard and Durakeys, privacy

Pointing Device

Glass ClickPad with multi-touch gesture support

Function Keys

F1 - Display Switching

F2 - Blank or Sure View

F3 - Brightness Down

F4 - Brightness up

F5 - Audio Mute

F6 - Volume Down

F7 - Volume Up

F8 - Mic Mute

F9 - Keyboard Backlight

F10 - Insert

F11 - Airplane Mode

F12 - Programmable Key

Non-Function Keys

HP Sure Shutter

Power Key

Delete Key

Hidden Function Keys

Fn+R = Break

Fn+S = Sys Rq

Fn+C = Scroll Lock

Fn+E = Insert

Fn+W = Pause



Technical Specifications

SOFTWARE AND SECURITY

Preinstalled Software

BIOS

HP BIOSphere Gen6 23

HP Drive Lock & Automatic Drive Lock

BIOS Update via Network

HP Secure Erase 24

Absolute Persistence Module 25

HP LAN-Wireless Protection

USB enable/disable (via BIOS)

Software

HP Connection Optimizer ²⁶

HP Hotkey Support

myHP

HP Support Assistant 27

HP QuickDrop 17

HP Noise Cancellation Software

Touchpoint Customizer for Commercial

HP Notifications

HP Privacy Settings

HP Wireless Button Driver

HP Power Manager

HP PC Hardware Diagnostics Windows

Buy Microsoft Office (sold separately)

Microsoft Defender 31

Tile App 32

HP Smart Support 53

Manageability Features

HP Driver Packs (download) 28

HP Manageability Integration Kit Gen4 (download) 29

HP Client Catalog (download)

HP Client Management Script Library (download)

HP Image Assistant (download)

Security Management

HP Client Security Manager Gen7 30

HP Fingerprint Sensor

HP Wolf Pro Security Edition³³

HP Sure Click 34

HP Sure Sense 35

HP Sure Start Gen6 36

HP Sure Admin 37

HP Sure Recover Gen4 38

HP Sure Run Gen4 39

TPM 2.0 Embedded Security Chip (Common Criteria EAL4+ Certified) (FIPS 140-2 Level 2 Certified) 40



Technical Specifications

- 17. HP Quick Drop requires Internet access and Windows 10 PC preinstalled with HP QuickDrop app and either an Android device (phone or tablet) running Android 7 or higher with the Android HP QuickDrop app, and /or an iOS device (phone or tablet) running iOS 12 or higher with the iOS HP QuickDrop app.
- 23. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. Features may vary depending on the platform and configurations.
- 24. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
- 25. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain conditions apply. For full details visit:

https://www.absolute.com/about/legal/agreements/absolute/

- 26. HP Connection Optimizer requires Windows 10.
- 27. HP Support Assistant requires Windows and Internet access.
- 28. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- 29. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html.

- 30. HP Client Security Manager Gen7 requires Windows and is available on the select HP Elite and Pro PCs.
- 31. Windows Defender Opt in and internet connection required for updates.
- 32. Some features require optional subscription to Tile Premium. Tile application for Windows 10 available for download from the Windows Store. Mobile phone app available for download from App Store and Google Play. Requires iOS 11 and greater or Android 6.0 and greater see https://support.thetileapp.com/hc/en-us/articles/200424778 for more information. HP Tile will function as long as the PC has battery power.
- 33. HP Wolf Pro Security Edition (including HP Sure Click Pro and HP Sure Sense Pro) is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following:
- "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.
- 34. HP Sure Click requires Windows 10 Pro or Enterprise. See https://bit.ly/2PrLT6A SureClick for complete details.
- 35. HP Sure Sense is available on select HP PCs and is not available with Windows 10 Home.
- 36. HP Sure Start Gen6 is available on select HP PCs.
- 37. HP Sure Admin requires Windows 10, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

- 38. HP Sure Recover Gen4 is available on select HP PCs and requires an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data.
- 39. HP Sure Run Gen4 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors.
- 40. Firmware TPM is version 2.0.
- 53. HP Smart Support is available to commercial customers through your HP Service Representative and HP Factory Configuration Services; or it can be downloaded at: http://www.hp.com/smart-support. HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights.



Technical Specifications

POWER

Power Supply

HP Smart 65 W USB Type-C[®] adapter ⁴¹ HP Smart 65 W Slim USB Type-C[®] adapter ⁴¹

Primary Battery

HP Long Life 4-cell, 54 Wh Li-ion polymer ^{42,43} HP Long Life 4-cell, 78.5 Wh Li-ion polymer ^{42,43}

Power Cord

Premium 1m C5 power cord Conventional 1m C5 power cord

Battery life 44

Up to 14 hours 45 minutes (54 Wh battery) (MobileMark2018). Up to 22 hours (78 Wh battery) (MobileMark2018)

- 41. Availability may vary by country.
- 42. Battery is internal and not replaceable by customer. Serviceable by warranty.
- 43. Actual battery Watt-hours (Wh) will vary from design capacity. Battery capacity will naturally decrease with shelf life, time, usage, environment, temperature, system configuration, loaded apps, features, power management settings and other factors.
- 44. Windows 10 MM18 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See www.bapco.com for additional details.

WEIGHTS & DIMENSIONS

Product Weight

Starting at 2.9 lb (1.31 kg) 45

Product Dimensions (w x d x h)

12.57 x 7.98 x 0.65 in 31.93 x 20.26 x 1.66 cm

45. Weight will vary by configuration.



PORTS/SLOTS

Ports

- 2 Thunderbolt[™] 4 with USB4[™] Type-C[®] 40Gbps signaling rate (USB Power Delivery, DisplayPort[™] 1.4)⁵²
- 2 SuperSpeed USB Type-A 5Gbps signaling rate (Charging ports)
- 1 HDMI 2.046
- 1 External Nano SIM Slot for WWAN 47
- 1 Headphone/Microphone Combo
- 46. HDMI cable sold separately.
- 47.SIM slot is not user accessible without WWAN configuration.
- 52. SuperSpeed USB 20Gbps is not available with Thunderbolt™ 4.

SERVICE AND SUPPORT

1-year or 3-year limited warranty and 90 day software limited warranty options depending on country.

Batteries have a default one year limited warranty except for HP Long Life batteries which will follow the one or three year warranty of the platform. Refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level

of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc. 48

48. HP Care Packs are sold separately. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit http://www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

ENERGY STAR® ⁴⁹
EPEAT® 2019 Gold in the U.S. ⁵⁰
Low halogen ⁵¹
TCO 8.0 Certified

- 49. Configurations of the HP EliteBook x360 1040 G8 Notebook PC that are ENERGY STAR® qualified are identified as HP EliteBook x360 1040 G8 Notebook PC ENERGY STAR on HP websites and on http://www.energystar.gov.
- 50. Based on US EPEAT® registration according to IEEE 1680.1-2018 EPEAT®. EPEAT® status varies by country. Visit http://www.epeat.net for more information.
- 51. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.



Technical Specifications

SYSTEM UNIT

Stand-Alone Power **Nominal Operating AC 15V Requirements (AC Power)**

Voltage

Average Operating Power

Integrated Graphics Yes **Discrete Graphics** N/A

Max Operating Power UMA<65W

Temperature Operating 32° to 95° F (0° to 35° C) (not writing optical)

> **Non-operating** 41° to 95° F (5° to 35° C) (writing optical)

Relative Humidity Operating 32° to 95° F (0° to 35° C) (not writing optical)

> **Non-operating** 5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature

Shock Operating 40 G, 2 ms, half-sine

> **Non-operating** 200 G, 2 ms, half-sine

Random Vibration Operating 1.043 grms

> **Non-operating** 3.5 grms

Altitude (unpressurized) Operating -50 to 10,000 ft (-15.24 to 3,048 m)

> **Non-operating** -50 to 40,000 ft (-15.24 to 12,192 m)

> > Yes

Planned Industry Standard

Certifications

UL Yes **CSA** Yes **FCC Compliance** Yes **ENERGY STAR®** Yes **EPEAT**

ICES Yes **Australia** Yes **NZ A-Tick Compliance** Yes

Yes **Japan VCCI Compliance** Yes

KC Yes **BSMI** Yes

CE Marking Compliance Yes **BNCI or BELUS** Yes CIT Yes GOST Yes

Saudi Arabian Compliance Yes

(ICCP)

SABS Yes **UKRSERTCOMPUTER** Yes



DISPLAYS

1. Actual brightness will be lower with touchscreen or Sure View.

Note: All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 14 inch FHD Outline
(1920.x.1080) Anti-Glare
WLED UWVA sRGB 100% cg
400nits eDP 1.4+PSR2 bent LP
Weight

 Outline Dimensions (W x H x D)
 313.67 X 184.17 mm (max)

 Active Area
 309.37 X 174.02 mm (typ.)

Weight 200 g (max)

Diagonal Size 14.0 inch

Thickness 2.0 mm/3.8 mm (w/PCB) (max)

InterfaceeDP 1.4Surface TreatmentAnti-GlareTouch EnabledYes

Contrast Ratio 1200:1 (typ.)

Refresh Rate 60 Hz **Brightness** 400 nits¹

Pixel Resolution 1920 x 1080 (FHD)

Format RGB Stripe

Backlight LED

Color Gamut Coverage sRGB 100% (NTSC 72%)

Color Depth 8 bits

Viewing Angle UWVA 85/85/85

Panel LCD 14 inch FHD (1920 x 1080) BrightView WLED UWVA sRGB 100% cg 400nits eDP 1.4+PSR2 bent LP

Panel LCD 14 inch FHD (1920 x Outline Dimensions (W x H x D)

 Outline Dimensions (W x H x D)
 313.67 X 184.17 mm (max)

 Active Area
 309.37 X 174.02 mm (typ.)

Weight 200 g (max)

Diagonal Size 14.0 inch

Thickness 2.0 mm/3.8 mm (w/PCB) (max)

Interface eDP 1.4
Surface Treatment BrightView

Touch Enabled Yes

Contrast Ratio 1200:1 (typ.)

Refresh Rate 60 Hz

Brightness 400 nits ¹

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB Stripe

Backlight LED

Color Gamut Coverage sRGB 100% (NTSC 72%)

Color Depth 8 bits

Viewing Angle UWVA 85/85/85

Panel LCD 14 inch UHD (3840 x Outline Dim 2160) BrightView WLED UWVA HDR-400 sRGB 95% cg 550nits Active Area eDP 1.4+PSR2 bent

Panel LCD 14 inch UHD (3840 x Outline Dimensions (W x H x D) 313.61 X 184.74 mm (max)

Active Area 309.31 X 173.98 mm (typ.)

Weight 200 g (max)

Diagonal Size 14.0 inch

Thickness 2.0 mm/3.8 mm (w/PCB) (max)

Interface eDP 1.4

Surface Treatment BrightView

Touch Enabled Yes

Contrast Ratio 1400:1 (typ.)

Refresh Rate 60 Hz **Brightness** 550 nits¹

Pixel Resolution 3840 x 2160 (UHD)

Format RGB Stripe

Backlight LED

Color Gamut Coverage SRGB 95%
Color Depth 8 bits+2FRC

Viewing Angle UWVA 85/85/85

Panel LCD 14-in FHD (1920 x 1080) Anti-Glare WLED UWVA 72% cg 1000nits eDP 1.4+PSR PrivacyG4 NB2Y **Outline Dimensions (W x H x D)** 314.612 x 185.33 mm (max.)

Active Area 309.312 x 173.99 mm

Weight 230 g (max.)

Diagonal Size 14.0"

Thickness 3.9 mm (max.)

Interface eDP

Surface Treatment Anti-glare

Touch Enabled Yes

Contrast Ratio 1500:1 (typ.)

Refresh Rate 60 Hz **Brightness** 1000 nits¹

Pixel Resolution 1920 x 1080 (FHD)

Format of LCD Pixel Arrangement RGB

Backlight LED

Color Gamut Coverage 72% of NTSC

Color Depth 8 bits

Viewing Angle UWVA 85/85/85

Panel LCD 14-in FHD (1920 x 1080) BrightView WLED UWVA 72% cg 1000nits eDP 1.4+PSR PrivacyG4 NB2Y **Outline Dimensions (W x H x D)** 314.612 x 185.33 mm (max.)

Active Area 309.312 x 173.99 mm

Weight 230 g (max.)

Diagonal Size 14.0"

Thickness 3.9 mm (max.)

Interface eDP

Surface Treatment BrightView

Touch Enabled Yes

Contrast Ratio 1500:1 (typ.)

Refresh Rate 60 Hz

Brightness 1000 nits¹

Pixel Resolution 1920 x 1080 (FHD)

Format RGB

Backlight LED

Color Gamut Coverage 72%

Color Depth 8 bits

Viewing Angle UWVA 85/85/85



STORAGE

SSD 128GB 2280 PCIe-3x2 Three Layer Cell

Form Factor M.2 2280
Capacity 128 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X2

 Maximum Sequential Read
 1300 ~ 2047 MB/s

 Maximum Sequential Write
 630 ~ 800 MB/s

 Logical Blocks
 250,069,680

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features ATA Security; DIPM; TRIM; DEVSLP

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 1TB 2280 PCIe-3x4 NVMe Form Factor Three Layer Cell single-sided

Form Factor M.2 2280
Capacity 1 TB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

InterfacePCIe NVMe Gen3X4Maximum Sequential Read3100 ~ 3500 MB/sMaximum Sequential Write2770 ~ 3037 MB/sLogical Blocks2,000,409,264

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security; TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.



SSD 256GB 2280 M2 PCIe-3x4 Form Factor SS NVMe TLC

Form Factor M.2 2280
Capacity 256 GB
NAND Type TLC

Logical Blocks

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 2800 ~ 3500 MB/s

 Maximum Sequential Write
 1400 ~ 2200 MB/s

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

500,118,192

Features ATA Security; TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 256GB 2280 PCIe NVMe Value Form Factor M.2 2280
Capacity 256 GB
NAND Type Value

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3

 Maximum Sequential Read
 2100 ~ 2200 MB/s

 Maximum Sequential Write
 900 ~ 1400 MB/s

 Logical Blocks
 500,118,192

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]
Features ATA Security (optional); TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 256GB 2280 PCIe-3x4 **NVMe Self Encrypted OPAL2 Three Layer Cell**

Form Factor M.2 2280 256 GB Capacity TLC **NAND Type**

Height Width 0.87 in (22 mm) 0.02 lb (10 q) Weight PCIe NVMe Gen3X4 Interface **Maximum Sequential Read** 2800 ~ 3500 MB/s 1663 ~ 2200 MB/s **Maximum Sequential Write** 500,118,192 **Logical Blocks**

32° to 158°F (0° to 70°C) [ambient temp] **Operating Temperature Features** ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

0.09 in (2.3 mm)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 512GB 2280 M2 PCIe-3x4 Form Factor SS NVMe TLC

M.2 2280 512 GB Capacity **NAND Type** TLC

0.09 in (2.3 mm) Height 0.87 in (22 mm) Width Weight 0.02 lb (10 g) PCIe NVMe Gen3X4 Interface **Maximum Sequential Read** 3100 ~ 3500 MB/s

2400 ~ 2956 MB/s **Maximum Sequential Write** 1,000,215,215 **Logical Blocks**

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

ATA Security; TRIM; L1.2 **Features**

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.



SSD 512GB 2280 PCIe NVMe Value

Form Factor M.2 2280
Capacity 512GB
NAND Type Value

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3

 Maximum Sequential Read
 2200 ~ 2300 MB/s

 Maximum Sequential Write
 1000 ~ 1600 MB/s

 Logical Blocks
 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp] **Features** ATA Security (optional); TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.

SSD 512GB 2280 PCIe-3x4 NVMe Self Encrypted OPAL2 Three Layer Form Factor M.2 2280
Capacity 512 GB
NAND Type TLC

 Height
 0.09 in (2.3 mm)

 Width
 0.87 in (22 mm)

 Weight
 0.02 lb (10 g)

 Interface
 PCIe NVMe Gen3X4

 Maximum Sequential Read
 3100 ~ 3500 MB/s

 Maximum Sequential Write
 2400 ~ 2956 MB/s

 Logical Blocks
 1,000,215,215

Operating Temperature 32° to 158°F (0° to 70°C) [ambient temp]

Features ATA Security (Option); TCG Opal 2.0; TRIM; L1.2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.



NETWORKING/COMMUNICATIONS

Intel Wi-Fi¹ 6 AX201 + BT5 (802.11ax 2x2, supporting gigabit file transfer speeds⁵) (vPro[®]) **Wireless LAN Standards**

IEEE 802.11a IEEE 802.11b IEEE 802.11q

IEEE 802.11n
IEEE 802.11ac
IEEE 802.11ac
IEEE 802.11d
IEEE 802.11d
IEEE 802.11h
IEEE 802.11h
IEEE 802.11h
IEEE 802.11r
IEEE 802.11r

Interoperability Features Wi-Fi 6 technology

Frequency Band 802.11b/g/n/ax

2.402 – 2.482 GHz
802.11a/n/ac/ax
4.9 – 4.95 GHz (Japan)

•5.15 – 5.25 GHz •5.25 – 5.35 GHz •5.47 – 5.725 GHz •5.825 – 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps •802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation Direct Sequence Spread Spectrum

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM

Security³ LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum power consumption

•IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certificationWPA3 certificationIEEE 802.11i



•WAPI

Network Architecture

Models

Roaming

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Output Power² • 802.11b: +18.5dBm minimum

• 802.11g: +17.5dBm minimum • 802.11a: +18.5dBm minimum

802.11n HT20(2.4GHz): +15.5dBm minimum
802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum

IEEE 802.11 compliant roaming between access points

802.11ax HT40(2.4GHz): +10dBm minimum
802.11ax VHT160(5GHz): +10dBm minimum

Power Consumption •Transmit mode:2.0 W

•Receive mode:1.6 W

Idle mode (PSP)180 mW (WLAN Associated)
 Idle mode:50 mW (WLAN unassociated)
 Connected Standby/Modern Standby: 10mW

•Radio disabled:8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ •802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
802.11n, MCS07: -67dBm maximum
802.11n, MCS15: -64dBm maximum

802.11ac, MCS0: -84dBm maximum
 802.11ac, MCS9: -59dBm maximum

•802.11ax, MCS11(HT40): -59dBm maximum •802.11ax, MCS11(VHT160): -58.5dBm maximum

Antenna type High efficiency antenna with spatial diversity, mounted in the display

enclosure

Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications

Form Factor PCI-Express M.2 MiniCard with CNVi Interface

Dimensions 1. Type 2230: 2.3 x 22.0 x 30.0 mm

2. Type 1216: 1.67 x 12.0 x 16.0 mm

Weight 1. Type 2230: 2.8g

2. Type 126: 1.3g

Operating Voltage 3.3v +/- 9%

Temperature Operating: 14° to 158° F (-10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

Humidity Operating: 10% to 90% (non-condensing)

Non-operating: 5% to 95% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)

Non-operating: 0 to 50,000 ft (15,240 m)

LED Activity LED Amber – Radio OFF; LED White – Radio ON

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification 4.0/4.1/4.2/5.0/5.1 Compliant

Frequency Band 2402 to 2480 MHz

Number of Available

Channels

Legacy: 0~79 (1 MHz/CH) BLE: 0~39 (2 MHz/CH)

Data Rates and Throughput Legacy: 3 Mbps data rate¹; throughput up to 2.17 Mbps BLE: 1 Mbps data rate¹; throughput up to 0.2 Mbps

1. Actual throughput may vary.

Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice

channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

Bluetooth Software

Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management ETS 300 328, ETS 300 826

Certifications Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer



LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full

LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

LE Data Packet Length Extension

FAX Profile (FAX)

Basic Imaging Profile (BIP)2

Headset Profile (HSP)

Hands Free Profile (HFP)

Advanced Audio Distribution Profile (A2DP)

Security & Manageability Intel® vPro™ support with appropriate Intel® chipset components

- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
- 2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.
- 3. Check latest software/driver release for updates on supported security features.
- 4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).
- 5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels.



Intel Wi-Fi¹ 6 AX201 + BT5 (802.11ax 2x2, supporting gigabit file transfer speeds⁵) (nonvPro®)

Wireless LAN Standards IEEE 802.11a

> IEEE 802.11b IEEE 802.11q

> IEEE 802.11n

IEEE 802.11ac

IEEE 802.11ax

IEEE 802.11d

IEEE 802.11e

IEEE 802.11h

IEEE 802.11i

IEEE 802.11k

IEEE 802.11r

IEEE 802.11v

Interoperability Features Wi-Fi 6 technology

Frequency Band 802.11b/g/n/ax

> •2.402 - 2.482 GHz 802.11a/n/ac/ax

•4.9 - 4.95 GHz (Japan)

•5.15 - 5.25 GHz

•5.25 - 5.35 GHz

•5.47 - 5.725 GHz

•5.825 - 5.850 GHz

Data Rates •802.11b: 1, 2, 5.5, 11 Mbps

•802.11q: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps

•802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)

•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

• 802.11ax: MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz &

160MHz)

Modulation **Direct Sequence Spread Spectrum**

OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM

, 1024QAM

Security³ •IEEE compliant 64 /128 bit WEP encryption for a/b/g mode only

•AES-CCMP: 128 bit in hardware

•802.1x authentication

•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.

WPA2 certification

WPA3 certification

•IEEE 802.11i

•WAPI



Network Architecture

Models

Ad-hoc (Peer to Peer)

Infrastructure (Access Point Required)

Roaming IEEE 802.11 compliant roaming between access points

Output Power² • 802.11b: +18.5dBm minimum

802.11g: +17.5dBm minimum
802.11a: +18.5dBm minimum

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802.11n HT40(2.4GHz): +14.5dBm minimum
802.11n HT20(5GHz): +15.5dBm minimum
802.11n HT40(5GHz): +14.5dBm minimum
802.11ac VHT80(5GHz): +11.5dBm minimum
802.11ac VHT160(5GHz): +11.5dBm minimum
802.11ax HT40(2.4GHz): +10dBm minimum

Power Consumption •Transmit mode 2.0 W

•Receive mode 1.6 W

Idle mode (PSP) 180 mW (WLAN Associated)Idle mode 50 mW (WLAN unassociated)

• 802.11ax VHT160(5GHz): +10dBm minimum

•Connected Standby 10mW

•Radio disabled 8 mW

Power Management ACPI and PCI Express compliant power management

802.11 compliant power saving mode

Receiver Sensitivity⁴ •802.11b, 1Mbps: -93.5dBm maximum

802.11b, 11Mbps: -84dBm maximum
802.11a/g, 6Mbps: -86dBm maximum
802.11a/g, 54Mbps: -72dBm maximum
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802.11n, MCS15: -64dBm maximum
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 802.11ax, MCS11(HT40): -59dBm maximum

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Weight 1. Type 2230: 2.8g

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Operating Voltage 3.3v +/- 9%

Temperature Operating: 14° to 158° F (–10° to 70° C)

Non-operating: -40° to 176° F (-40° to 80° C)

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Non-operating: 5% to 95% (non-condensing)

Altitude Operating: 0 to 10,000 ft (3,048 m)

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1. Actual throughput may vary.

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channels

Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps

asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)

Transmit Power The Bluetooth component shall operate as a Class II Bluetooth device with

a maximum transmit power of + 9.5 dBm for BR and EDR.

Power Consumption Peak (Tx): 330 mW

Peak (Rx): 230 mW

Selective Suspend: 17 mW

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Supported Link Topology Microsoft Windows Bluetooth Software

Power Management Microsoft Windows ACPI, and USB Bus Support

Certifications FCC (47 CFR) Part 15C, Section 15.247 & 15.249

Power Management

Certifications

ETS 300 328, ETS 300 826

Low Voltage Directive IEC950

UL, CSA, and CE Mark

Bluetooth Profiles

Supported

BT4.1-ESR 5/6/7 Compliance

LE Link Layer Ping

LE Dual Mode LE Link Layer

LE Low Duty Cycle Directed Advertising
LE L2CAP Connection Oriented Channels

Train Nudging & Interlaced Scan

BT4.2 ESR08 Compliance

LE Secure Connection- Basic/Full LE Privacy 1.2 -Link Layer Privacy

LE Privacy 1.2 - Extended Scanner Filter Policies

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FAX Profile (FAX)

Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)

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- 1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices. Only available in countries where 802.11ax is supported.
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- 5. Wi-Fi 5 or 6 is designed to support gigabit data rate when transferring files between two devices connected to the same router. Requires a wireless router, sold separately, that supports 80MHz and higher channels

Intel® XMM™ 7360 LTE-Advanced¹

Technology/Operating

bands

LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700 (Band 4),

850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12),

700 (Band 13)

FDD LTE:

700 (Band 17), 850 (Band 18), 850 (Band 19), 800 (Band 20), 1450 (Band

21), 850 (Band 26)

700 (Band 28) MHz, 700 (Band 29), 2300 (Band 30), 2100 (Band 66) MHz

TDD LTE:

2600 (Band 38), 1900 (Band 39), 2300 (Band 40), 2500 (Band 41) MHz HSPA+: 2100 (Band 1), 1900 (Band 2), 1700 (Band 4), 850 (Band 5), 900

(Band 8) MHz

Wireless protocol

standards

3GPP Release 11 LTE Specification CAT.9, MAX 60MHz aggregation BW

WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-B and LTO)

GPS bands GPS 1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz, Beidou

1561.098 ± 2.046 MHz

Maximum data rates LTE: 450 Mbps (DL 3CA), 50 Mbps (Upload)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload)

HSPA+: 21Mbps (Download), 5.76 Mbps (Upload)

Maximum output power LTE: 23 dBm

HSPA+: 23.5 dBm

Maximum powerLTE: 1,200 mA (peak); 900 mA (average)consumptionHSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 6 q

Dimensions 42 x 30 x 2.3 mm

(Length x Width x

Thickness)

1. WWAN module is an optional feature, requires factory configuration and requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. LTE not available on all products, in all regions.

Qualcomm® Snapdragon™ X55 5G Modem (5G + LTE CAT 20) ¹

Technology/Operating bands

WCDMA/HSDPA/HSUPA/HSPA+ operating bands:

Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)
Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
Band 6: 830 to 840 MHz (UL), 875 to 885 MHz (DL)
Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
Band 9: 1750 to 1785 MHz (UL), 1845to 1880 MHz (DL)
Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL)

LTE FDD/TDD operating bands:

Band 1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
Band 2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
Band 3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
Band 4: 1710 to 1755 MHz (UL), 2110 to 2155 MHz (DL)
Band 5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
Band 7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)
Band 8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
Band 12: 699 to 716 MHz (UL), 729 to 746 MHz (DL)
Band 13: 777 to 787 MHz (UL), 746 to 756 MHz (DL)
Band 14: 788 to 798 MHz (UL), 758 to 768 MHz (DL)
Band 17: 704 to 716 MHz (UL), 860 to 875 MHz (DL)
Band 18: 815 to 830 MHz (UL), 860 to 875 MHz (DL)

Band 19: 830 to 845 MHz (UL), 875 to 890 MHz (DL) Band 20: 832 to 862 MHz (UL), 791 to 821 MHz (DL) Band 25: 1850 to 1915 MHz (UL), 1930 to 1995 MHz (DL) Band 26: 814 to 849 MHz (UL), 859 to 894 MHz (DL)

Band 28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)



Band 29: 717 to 728 MHz (DL)

Band 30: 2305 to 2315 MHz (UL) 2350 to 2360 MHz (DL)

Band 32: 1452 to 1496 MHz (DL) Band 34: 2010 to 2025 MHz (UL/DL) Band 38: 2570 to 2620 MHz (UL/DL) Band 39: 1880 to 1920 MHz (UL/DL) Band 40: 2300 to 2400 MHz (UL/DL)

Band 41: 2496 to 2690 MHz (UL/DL) Band 42: 3400 to 3600 MHZ (UL/DL)

Band 46: 5150 to 5925 MHZ (DL) Band 48: 3550 to 3700 MHZ (UL/DL)

Band 66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) Band 71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)

5GNR Sub 6GHZ

n1: 1920 to 1980 MHz (UL), 2110 to 2170 MHz (DL)
n2: 1850 to 1910 MHz (UL), 1930 to 1990 MHz (DL)
n3: 1710 to 1785 MHz (UL), 1805 to 1880 MHz (DL)
n5: 824 to 849 MHz (UL), 869 to 894 MHz (DL)
n7: 2500 to 2570 MHz (UL), 2620 to 2690 MHz (DL)
n8: 880 to 915 MHz (UL), 925 to 960 MHz (DL)
n12: 699 to 716 MHz (UL), 729 to 746 MHz (DL)
n20: 832 to 862 MHz (UL), 791 to 821 MHz (DL)
n28: 703 to 748 MHz (UL), 758 to 803 MHz (DL)

n41: 2496 to 2690 MHz (UL/DL)

n66: 1710 to 1800 MHz (UL), 2110 to 2200 MHz (DL) n71: 663 to 698 MHz (UL), 617 to 652 MHz (DL)

n77: 3300 to 4200 MHz (UL/DL) n78: 3300 to 3800 MHz (UL/DL) n79: 4400 to 5000 MHz (UL/DL)

5GNR Air Interface

Wireless protocol standards

l 3GPP Rel15 5G NR sub-6

LTE Rel14

20 layers and 2 Gbps downlink (DL) throughput - 4 × 4 MIMO across 5x CA

200 Mbps uplink (UL) throughput - 40 MHz ULCA and 256 QAM

WCDMA

R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification

GPS Standalone, A-GPS (MS-A, MS-B)

GPS: L1 (1575.42MHz); L5 (1176MHz)

GPS bands GLONASS: L1 (1602MHz)
BeidouB1(1561.098MHz)

Galileo E1 (1575.42); E5a (1176MHz)

5G sub 6G: 3.8 Gbps

LTE: ue-CategoryDL 20, (DL : 2 Gbps)

Maximum data rates ue-CategoryUL 13, (UL: 150Mbps)

DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21 Mbps (Download), 5.76 Mbps (Upload)

Technical Specifications

Maximum output

LTE: 23 dBm in all band except B41

power LTE B41 HPUE = 26dBm

HSPA+: 23.5 dBm

5G Sub 6: 2500 mA

Maximum power consumption LTE: 1,300 mA (peak); 1100 mA (average)

HSPA+: 1,100 mA (peak); 800 mA (average)

Form Factor M.2, 3042-S3 Key B

Weight 8 g

Dimensions

(Length x Width x 42 m \times 30 mm \times 2.6 mm

Thickness)

1. 5G module is an optional feature that must be configured at purchase. AT&T and T-Mobile networks supported in the U.S. Module designed for 5G networks as carriers deploy Evolved-Universal Terrestrial Radio Access New Radio Dual Connectivity (ENDC) with both 100Mhz of 5G NR and LTE channel bandwidth, using 256QAM 4x4 as defined by 3GPP, requires activation and separately purchased service contract. Check with service provider for coverage and availability in your area. Connection, upload and download speeds will vary due to network, location, environment, network conditions, and other factors. 5G not available on all products, in all regions. Backwards compatible to 4G LTE and 3G HSPA technologies. 5G module planned to be available in select countries, where carrier supported.



NXP NPC300 Near Field Communication Module

Dimensions (L x W x H) Module 17 mm by 10 mm by 2.0 mm

Chipset NPC300

System interface 12C

NFC RF standards ISO/IEC 14443 A

ISO/IEC 14443 B ISO/IEC 15693 ISO/IEC 18092

ECMA-340 NFCIP-1 Target and Initiator

ECMA-320 NFCIP-2

NFC Forum Support Tag Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2

Reader (PCD-VCD)
Mode(1)

CD-VCD) ISO/IEC 14443 A ISO/IEC 14443 B

ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire

FeliCa

Jewel and Topaz cards

Card Emulation (PICC-VICC) Mode(1) ISO/IEC 14443 A

ISO/IEC 14443 B and B'

MIFARE FeliCa

Frequency 13.56 MHz

NFC Modes Supported Reader/Writer, Peer-to-Peer

Raw RF Data Rates 106, 212, 424, 848 kbps

Operating temperature -25°C to 80°C

Storage temperature -25°C to 125°C

Humidity 10-90% operating

5-95% non-operating

Supply Operating

voltage

2.7 to 5.5 Volts

I/O Voltage 1.8V or 3.3V

Power Consumption (Booster enable, VBAT= 3.3V, VCC_BOOST = 5V)

Mode Power Consumption, Typical (2)

Polling 710.93 mW

Detected Test Tag Type 1 152.09 mW

Detected Test Tag Type 2 341.26 mW

Detected Test Tag Type 3 383.76 mW



Detected Test Tag Type 4 312.26 mW

Antenna

Antenna connector, 0.3mm pitch, 7 connector FPC. Antenna matching is external to module.

- 1. With application or UICC support
- 2. Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured.



POWER

AC Adapter 65 Watt nPFC Slim USB type C Straight 1.0 m

Dimensions Weight Input

88 x 53.5 x 21mm unit: 220g +/- 10g 100 to 240 VAC **Input Efficiency**

81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A 47 ~ 63 Hz

Input frequency range

Input AC current

1.6 A at 90 VAC and maximum load

Output power 65W

> **DC** output 5V/9V/12V/15V/20V Hold-up time 5ms at 115 Vac input

Output current limit < 8.0A

Connector

Output

Environmental Design

Operating temperature

Non-operating (storage)

temperature

USB Type C

32oFto 95oF (Ooto 35oC)

-4oFto 185oF (-20oto 85oC)

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity 5% to 95% **Storage Humidity** 5% to 95%

EMI and Safety Certifications

Eg:

*CE Mark - full compliance with LVD and EMC directives

* Worldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B,

FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE.

* MTBF - over 100,000 hours at 25°C ambient condition.

AC Adapter 65 Watt nPFC Dimensions Standard USB type C Straight 1.0 m

Weight Input

90.0 x 51 x 28.5mm unit: 250g +/- 10g 100 to 240 VAC

Input Efficiency 81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A

88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A 89% min at 115 Vac/ 230Vac @ 20V/3.25A

Input frequency range

Input AC current 1.6 A at 90 VAC and maximum load

47 ~ 63 Hz

Output **Output power** 65W

> DC output 5V/9V/12V/15V/20V Hold-up time 5ms at 115 Vac input

Output current limit 8.0A Max.

Connector **USB TYPE C**

Environmental Design Operating temperature 32°F to 95°F (0°to 35°C)

Non-operating (storage) -4°F to 185°F (-20°to 85°C)

temperature

Altitude 0 to 16,400 ft (0 to 5000m)

Humidity20% to 95%Storage Humidity10% to 95%

EMI and Safety Certifications - CE Mark - full compliance with LVD and EMC directives

- Worldwide safety standards -IEC60950, EN60950, UL60950, UL62368, Class1, SELV; Agency approvals - C-UL-US, NORDICS, DENAN, EN55022

Class B, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE. - MTBF - over 200,000 hours at 25°C ambient condition.

Battery HK 4 Cell Wh 54 Long Life -PL **Dimensions** (H x W x L) 5.85mm*89.7mm*268.2mm

Weight 221g±10g
Cells/Type 4-cell; Polymer

Energy Voltage 7.7V

Amp-hour capacity7.013AhWatt-hour capacity54WhOperating (Charging)0~45°C

Temperature Operating (Discharging) $-10^{\circ}\text{C}\sim60^{\circ}\text{C}$

Fuel Gauge LED No

Optional Travel Battery

Available

N/a

Battery HK 4 Cell WH 78 Long Life -PL **Dimensions** (H x W x L) 6.49mm*94.6mm*281.6mm

Weight 295g±10g
Cells/Type 4-cell; Polymer

Energy Voltage 7.72V

Amp-hour capacity 10.18Ah
Watt-hour capacity 78.5Wh
Operating (Charging) 0~45°C

Temperature Operating (Discharging) $-10^{\circ}\text{C}\sim60^{\circ}\text{C}$

Fuel Gauge LED No

Optional Travel Battery

Available

N/A

Technical Specifications

FINGERPRINT READER Model:

Synaptics Validity VFS7604 touch sensor

Mobile Voltage Operation:

3.0V to 3.6V

Operating Temperature:

0~60°C

Current Consumption Image:

100mA Max

Low Latency Wait For Finger:

260 uA

Capture Rate:

Image transmitter output frequency 9.6MHz

ESD Resistance:

IEC 61000-4-2 4B (+/-15KV)

Detection Matrix:

363 dpi / 7.4x6mm sensor area

FRR (False Reject Rate) / FAR (False Acceptance Rate):

FRR <1% @ 1:50K FAR



Technical Specifications

ENVIRONMENTAL DATA

Eco-Label	This product has received or is in the process of being certified to the following approvals and may			
Certifications &				
declarations	 be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR® US Federal Energy Management Program (FEMP) EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO 8.0 China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label* 			
Sustainable Impact	Ocean-bound plastic in (part(s)) ¹		
Specifications	• 24.71% post-consumer recycled plastic ²			
	• External Power Supply 9	0% Efficiency		
	• Low halogen ³			
	• Outside Box and corrugated cushions are 100% sustainably sourced and recyclable ⁴			
	 Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable⁵ Recycled Plastic cushions ⁶ Bulk packaging available 			
 Percentage of ocean-bound plastic contained in each component varies by processing the second plastic content percentage is based on the definition set in the IEEE standard. External power supplies, WWAN modules, power cords, cables and peripherals 4. 100% outer box packaging and corrugated cushions made from sustainably strecycled fibers. Fiber cushions made from 100% recycled wood fiber and organic materials. Plastic cushions are made from >90% recycled plastic. 			definition set in the IEEE 1680.1-2018 rds, cables and peripherals excluded. made from sustainably sourced certified and r and organic materials.	
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the			
	Notebook model is based on a "Typically Configured Notebook".			
Energy Consumption				
(in accordance with US				
ENERGY STAR® test				
method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation	8.47 W	8.56 W	8.50 W	
(Sort idle)	0.03.14	0.01 W	0.70 W	
Normal Operation	0.82 W	0.81 W	0.78 W	
(Long idle)	0.03.14	0.81 W	0.78 W	
Sleep	0.82 W	U.81 W	U. / 8 W	



Technical Specifications

Off	0.30 W	0.32 W	0.29 W		
	family. HP computers man Environmental Protection family does not offer ENE	ked with the ENEF Agency (EPA) EN RGY STAR® complia PC featuring a h	RGY STAR' ERGY STA ant config	compliant product if offered within the model ** Logo are compliant with the applicable U.S. R** specifications for computers. If a model jurations, then energy efficiency data listed is drive, a high efficiency power supply, and a	
Heat Dissipation*	115VAC, 60Hz	SVAC, 60Hz 230VAC, 50Hz		100VAC, 50Hz	
Normal Operation (Short idle)	27 BTU/hr	27 BTU/hi		27 BTU/hr	
Normal Operation (Long idle)	3 BTU/hr	3 BTU/hr		2 BTU/hr	
Sleep	3 BTU/hr	3 BTU/hr		2 BTU/hr	
Off	1 BTU/hr	1 BTU/hr		1 BTU/hr	
	*NOTE: Heat dissipation is attained for one hour.	calculated based	on the m	neasured watts, assuming the service level is	
Declared Noise	Sound Power		Sound Pressure		
Emissions (in accordance with ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(L _{pAm} , decibels)		
Typically Configured – Idle	2.6			14.4	
Fixed Disk – Random writes	2.9			14.4	
Optical Drive – Sequential reads	3.1			29.1	
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.				
Additional Information	 This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC. This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC. This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986). This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net Plastics parts weighing over 25 grams used in the product are marked per IS011469 and IS01043. This product is 24.7% recycle-able when properly disposed of at end of life. 				



Technical Specifications

Packaging Materials	External:	PAPER/Corrugated	222 g	
	Internal:	PLASTIC/polypropylene	3 g	
		PLASTIC/Polyethylene low density	8 g	
		PAPER/paperboard	51 g	
	PAPER/Molded pulp 154 g			
	The plastic packaging material contains at least 0% recycled content. The corrugated paper packaging materials contains at least 59% recycled content.			
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.			
Material Usage	the HP Gene http://www. • Asb	does not contain any of the following substances in ral Specification for the Environment at: hp.com/hpinfo/globalcitizenship/environment/supplestos		
	 Cer Cad Chl Biss Ber Dib 	tain Azo Colorants tain Brominated Flame Retardants — may not be used Imium orinated Hydrocarbons orinated Paraffins (2-Ethylhexyl) phthalate (DEHP) uzyl butyl phthalate (BBP) utyl phthalate (DBP)	d as flame retardants in plastics	
	 For Hal Lea Mei Nici har Ozo Pol 	sobutyl phthalate (DIBP) maldehyde ogenated Diphenyl Methanes d carbonates and sulfates d and Lead compounds curic Oxide Batteries kel – finishes must not be used on the external surface adled or carried by the user. one Depleting Substances ybrominated Biphenyls (PBBs) ybrominated Biphenyl Ethers (PBBEs)	ce designed to be frequently	
	PolPol	ybrominated Biphenyl Oxides (PBBOs) ychlorinated Biphenyl (PCB) ychlorinated Terphenyls (PCT) yvinyl Chloride (PVC) — except for wires and cables, ar	nd certain retail packaging has bee	

	valuntarily removed from most applications		
	voluntarily removed from most applications. • Radioactive Substances		
	 Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO) 		
	Iributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)		
Danka din a Propinsi			
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:		
	Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in		
	packaging materials.		
	 Eliminate the use of ozone-depleting substances (ODS) in packaging materials. 		
	 Design packaging materials for ease of disassembly. 		
	 Maximize the use of post-consumer recycled content materials in packaging materials. 		
	 Use readily recyclable packaging materials such as paper and corrugated materials. 		
	 Reduce size and weight of packages to improve transportation fuel efficiency. 		
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards. 		
End-of-life	HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle		
Management and	your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales		
Recycling	office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.		
	The FILWESS directive (2002/05/EC) requires manufacturers to provide treatment information for		
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for		
	each product type for use by treatment facilities. This information (product disassembly		
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These		
	instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM		
	customers who integrate and re-sell HP equipment.		
HP, Inc. Corporate	For more information about HP's commitment to the environment:		
Environmental			
Information	Global Citizenship Report		
ini oi iliation	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications		
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html		
	ISO 14001 certificates:		
	http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842		
	and		
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf		
	I		

COUNTRY OF ORIGIN

China



Options and Accessories (sold separately and availability may vary by country)

•	Description	Part #
Type Cases	-	
cases	HP Business Slim 14.1 Top Load	2SC65AA, 2SC65UT, 2SC65ET
	HP Executive 15.6 Backpack	6KD07AA, 6KD07UT, 6KD07ET
	HP Executive Slim 14.1 Top Load	6KD04AA, 6KD04UT, 6KD04ET
Docking	HP Thunderbolt 120W Dock G2	6HP48AA, 2UK37AA, 2UK37ET
	HP Thunderbolt 120W Dock w/Audio G2	3YE87AA, 2UK37UT, 3YE87ET
	HP Thunderbolt 230W Dock w/Combo Cable G2	3TR87AA, 3TR87UT, 3TR87ET
	HP USB-C 120W G5 Dock	26D32AA, 5TW10AA, 5TW10UT, 5TW10ET
	HP USB-C Mini Dock	2SR85AA, 1PM64AA, 1PM64UT, 1PM64ET
	HP USB-C/A 120W Universal Dock G2	5TW13AA, 5TW13UT, 5TW13ET
Input/Output	HP HDMI to VGA Adapter	H4F02AA, H4F02UT, H4F02ET
	HP TB Dock 120W G2 Cable	3XB94AA, 3XB94UT, 3XB94ET
	HP TB Dock 230W G2 Combo Cable	3XB96AA, 3XB96UT, 3XB96ET
	HP USB-C to DisplayPort Adapter	N9K78AA, N9K78UT
	HP USB-C to HDMI 2.0 Adapter	2PC54AA, 1WC36UT, 1WC36AA
	HP USB-C to RJ45 Adapter	V8Y76AA, V7W66AA, V7W66UT
	HP USB to Gig RJ45 Adapter	N7P47AA
	HP USB-C to USB-A Hub	Z8W90AA, Z6A00AA, Z6A00UT, Z6A00ET
	HP USB Collaboration Keyboard	Z9N38AA, Z9N38UT
	HP Wireless USB Premium Keyboard	Z9N41AA, Z9N41AT
	HP WL BT Collaboration Keyboard	Z9N39AA, Z9N39UT
	HP WL USB Keyboard	T6U20AA, T6U20UT
	HP Slim Wireless Keyboard and Mouse	T6L04AA, T6L04UT
	HP Wired Desktop 320MK Mouse and Keyboard	9SR36AA, 9SR36UT, 9SR36ET
	HP Wireless Rechargeable 950MK Mouse and Keyboard	3M165AA
	HP 235 WL Mouse and Keyboard Combo	1Y4D0AA
	HP 125 Wired Keyboard	266C9AA
	HP 320M Wired Mouse	9VA80AA, 9VA80UT, 9VA80ET
	HP Comfort Grip Wireless USB Mouse	H2L63AA, H2L63UT
	HP Presenter Bluetooth Mouse	2CE30AA, 2CE30UT, 2CE30ET
	HP Travel Bluetooth Mouse	6SP30AA, 6SP30UT, 6SP30ET
	HP Travel USB Mouse	G1K28AA, G1K28ET
	HP UltraMobile Wireless Mouse	H6F25AA, H6F25UT
	HP Active RECHBL Pen G3	6SG43AA, 6SG43UT



Options and Accessories (sold separately and availability may vary by country)

Power HP 65W USB-C AC Power Adapter 1HE08AA, 1HE08UT

HP 65W USB-C LC AC Power Adapter 1P3K6AA, 1P3K6UT

HP 65W USB-C Slim Travel AC Power Adapter X7W50AA, 3PN48AA, 3PN48UT

HP USB Power Bank

HP USB-C Essential Power Bank 3TB55AA, 3TB55UT

Storage HP USB DVD-Writer EXT ODD Y3T76AA, F2B56AA, F2B56UT,

F2B56ET

N9F71AA, N9F71UT

Security HP Dual Head Nano Cable Lock 1AJ41AA, 1AJ41UT

HP Nano Cable Lock 1AJ39AA, 1AJ39UT
HP SureKey Standard/Nano/Wedge Cable Lock 6UW42AA, 6UW42UT

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UCC HP BT UC WL Duo Headset W3K09AA#ABB, W3K09AA#UUF

HP Wired Thunderbolt Audio Module 3AQ21AA, 3AQ21UT, 3AQ21ET

HP Wired USB-A Stereo Headset T1A67AA

HP Wireless BT UC WL Mono Headset W3K08AA#ABB, W3K08AA#UU

Summary of Changes

Date of change:	Version History:		Description of change:
January 27, 2021	V1 to V2	Update	USB ports to new industry standards, WPA3 certification
February 10, 2021	V2 to V3	Added	Environmental Data
February 17, 2021	V3 to V4	Update	Environmental Data
March 2, 2021	V4 to V5	Update	Battery Life
March 15, 2021	V5 to V6	Update	Battery Life
April 19, 2021	V6 to V7	Updated	Input/ Output Section Updated
May 6, 2021	V7 to V8	Removed	Processors base frequency/Added HP Smart Support
May 27, 2021	V8 to V9	Updated	HP Pro Security Edition to HP Wolf Pro Security Edition
June 11, 2021	V9 to V10	Removed	HP WorkWell from Software and Security section

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